IEEE ELECTRONICS PACKAGING SOCIETY

MANAV RACHNA
vidyanatariksha

INSTITUTION'S INNOVATION COUNCIL
(Ministry of Education Initiative)

1st International Electronics & Packaging Technologies Conference 2026

Bridging Skills & Innovation for India's Industry (EPT India)

2nd & 3rd March, 2026

Organized by

Manav Rachna International Institute of Research And Studies

Technical Sponsor

IEEE Electronics Packaging Society

About the Conference

Set amidst the scenic Aravalli Hills, EPTC INDIA 2026 is an international platform for academia, industry, and government to explore the latest innovations in electronics and packaging technologies. The conference will feature:

- Keynotes & invited talks
- Tutorials & workshops
- Technical sessions & panels
- Exhibitions & networking activities

Expected participants: ~**250 professionals from academia & industry**

Themes & Topics

Advanced Packaging Technologies

- Heterogeneous Integration & System-in-Package (SiP)
- Fan-Out Wafer-Level Packaging (FOWLP)
- 3D IC & Through-Silicon Vias (TSVs)
- Advanced Substrates & Interposers

Materials & Processes for Packaging

- High-Performance Packaging Materials
- Thermal Interface Materials (TIMs)
- Soldering, Adhesives & Encapsulation
- Additive Manufacturing & 3D Printing

Reliability & Testing

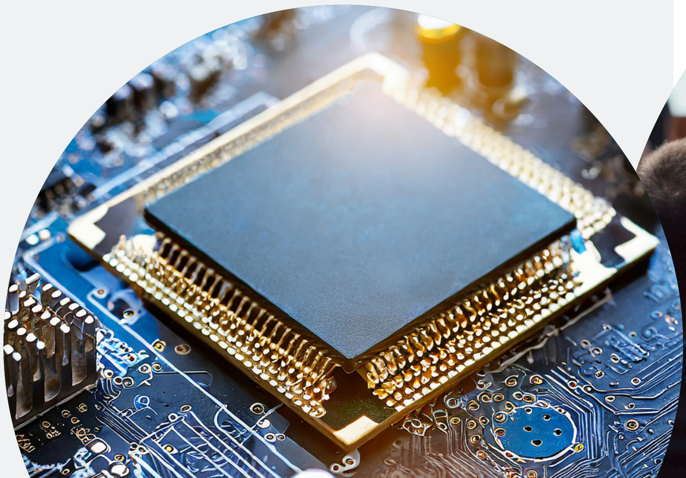
- Failure Analysis & Reliability Testing
- Mechanical & Thermal Stress Testing
- Advanced Metrology
- AI-Driven Predictive Maintenance

Power & RF Packaging

- Power Electronics & Thermal Management
- RF Applications Packaging
- Wide Bandgap Semiconductors (SiC, GaN)
- EMI Shielding

Emerging Applications

- IoT & Wearable Devices
- Quantum Computing
- Automotive & Aerospace
- Biocompatible & Medical Devices



Sustainable & Green Packaging

- Eco-Friendly Materials
- Circular Economy Practices
- Low-Carbon Manufacturing
- Lifecycle Assessment

Advanced Interconnects & Integration

- High-Density, Flexible & Stretchable Electronics
- Optical & Wireless Interconnects
- Photonic & Antenna Integration

Thermal & Mechanical Challenges

- Heat Dissipation & Thermal Modeling
- Advanced Cooling Solutions
- Thermal Interface Materials

AI, ML & Digital Twin in Packaging

- AI-Driven Design & Optimization
- Machine Learning for Predictive Analysis
- Digital Twins for Testing
- Automation & Robotics

Industry Trends & Standards

- Standardization in Processes & Materials
- Academia-Industry Collaboration
- Future Trends in Semiconductor Packaging
- Case Studies of Innovation

Tutorials & Workshops

SME-led sessions aligned with AICTE/ESSCI approved curriculum for **faculty development, industry,** and **student engagement.**

Manufacturing Skills Workshops

- Industrial Safety for Semiconductors
- Vacuum Technology
- OSAT Manufacturing & Wafer Dicing
- Cleanroom & Ultra-Pure Water Technologies

Design Skills Workshops

- Semiconductor Manufacturing Simulation with LAM Semulator 3D
- Altium PCB Design & Manufacturing

Important Dates

Call for Papers opens on 15th July, 2025

Full Manuscript Submission Deadline: 1st December, 2025

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Do not miss this opportunity to be part of International EPTC 2026 – Delhi NCR!